

HSF COMPLIANT

NOTE:
1. FLASH NOT EXCEED 0.05mm.
2. DIM. MARKED ☒ SHOULD BE MEASURED BY FAI.
3. DIM. MARKED ▼ SHOULD BE CONTROLLED BY QC.
4. PART No:

PART NO.: FP0510X-0XX X X GL
PIN NO. X X GL
PACKING:
0:TAPE & REEL
1:TUBE
CONTACTS PLATING:
G: Au 1~3u"
T: Au 3u"
A: Au 5u"
1: Au 10u"
3: Au 30u"

"A" CABLE T=0.30mm.
COVER COLOR: BLACK.
"B" CABLE T=0.20mm.
COVER COLOR: BLUE.

SECTION A-A

BOM:

HOUSING	LCP	UL94 V-0, COLOR: NATURAL
COVER	LCP OR HTN OR PA9T	UL94 V-0
PEG<L>	P/B C5210-SH, T=0.15	Sn
PEG<R>	P/B C5210-SH, T=0.15	Sn
TERMINAL	P/B C5210-SH, T=0.15	CONTACT AREA: Au(SEE P/N) SOLDER AREA: Au(2.5u" MIN)
DESC.	MATERIAL	REMARKS

DIM	TOL	DEC	TOL
X.	±--	X.*	±2°
X.X	±0.15	X.X*	±--
X.XX	±0.05	X.XX*	±--
X.XXX	±--	X.XXX*	±--

SHEET:	1/2	UNIT	mm	SCALE	10:1	SIZE	A4	REV	A1
DRWN:	Qing Wang 4/20'13	PART NO.:	FP0510X-0XXXXGL						
CHKD:	Jack Wang 4/20'13	TITLE:	0.5P 1.0H FPC (BACK-FLIP)-ASSY						
APPD:	Bob Sun 4/22'13	DRAWING NO.:							

G: Au 1~3u"
T: Au 3u"
A: Au 5u"
1: Au 10u"
3: Au 30u"

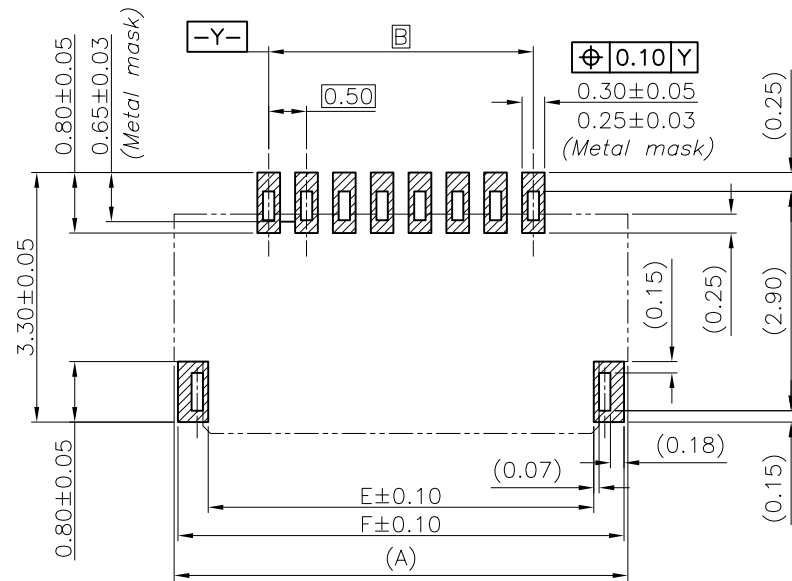
SECTION A-A

HOUSING	LCP	UL94 V-0, COLOR: NATURAL
COVER	LCP OR HTN OR PA9T	UL94 V-0
PEG<L>	P/B C5210-SH, T=0.15	Sn
PEG<R>	P/B C5210-SH, T=0.15	Sn
TERMINAL	P/B C5210-SH, T=0.15	CONTACT AREA: Au(SEE P/N) SOLDER AREA: Au(2.5u" MIN)
DESC.	MATERIAL	REMARKS

UNIT	SCALE	SIZE	REV
mm	10:1	A4	A1

DIM	TOL	DEC	TOL
X.	±---	X.*	±2°
X.X	±0.15	X.X*	±---
X.XX	±0.05	X.XX*	±---
X.XXX	±---	X.XXX*	±---

HSF COMPLIANT

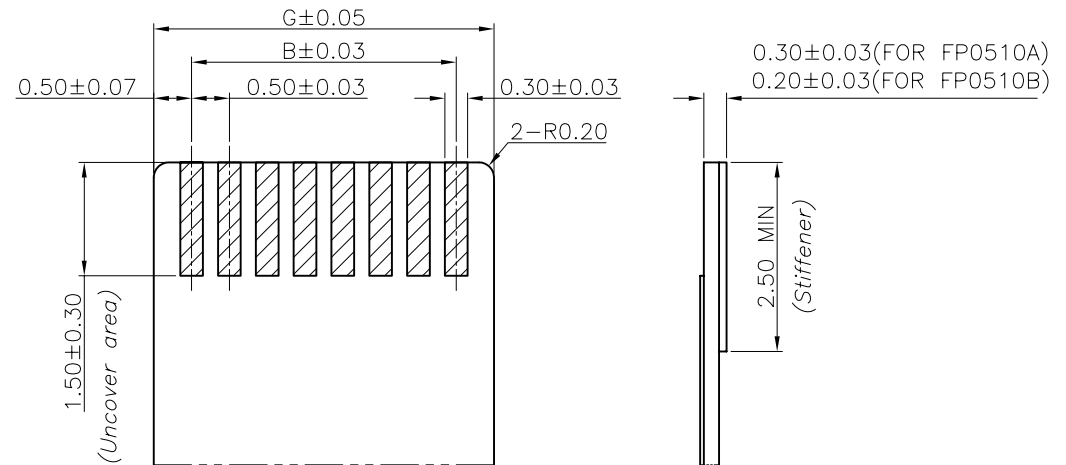


Recommended PCB mounting pattern and metal mask dimensions

Recommended metal mask thickness: $t=0.1$

(N)	$N*0.5+2.0$	$(N-1)*0.5$	$N*0.5+0.57$	$N*0.5+1.39$	$N*0.5+1.1$	$N*0.5+1.9$	$N*0.5+0.5$
50	27.00	24.50	25.57	26.39	26.10	26.90	25.50
42	23.00	20.50	21.57	22.39	22.10	22.90	21.50
40	22.00	19.50	20.57	21.39	21.10	21.90	20.50
36	20.00	17.50	18.57	19.39	19.10	19.90	18.50
34	19.00	16.50	17.57	18.39	18.10	18.90	17.50
32	18.00	15.50	16.57	17.39	17.10	17.90	16.50
30	17.00	14.50	15.57	16.39	16.10	16.90	15.50
26	15.00	12.50	13.57	14.39	14.10	14.90	13.50
24	14.00	11.50	12.57	13.39	13.10	13.90	12.50
23	13.50	11.00	12.07	12.89	12.60	13.40	12.00
22	13.00	10.50	11.57	12.39	12.10	12.90	11.50
20	12.00	9.50	10.57	11.39	11.10	11.90	10.50
16	10.00	7.50	8.57	9.39	9.10	9.90	8.50
14	9.00	6.50	7.57	8.39	8.10	8.90	7.50
12	8.00	5.50	6.57	7.39	7.10	7.90	6.50
11	7.50	5.00	6.07	6.89	6.60	7.40	6.00
10	7.00	4.50	5.57	6.39	6.10	6.90	5.50
8	6.00	3.50	4.57	5.39	5.10	5.90	4.50
7	5.50	3.00	4.07	4.89	4.60	5.40	4.00
6	5.00	2.50	3.57	4.39	4.10	4.90	3.50
4	4.00	1.50	2.57	3.39	3.10	3.90	2.50
Number of Contacts	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G

1 A3



Recommended FPC/FFC Dimensions

HSF STD				CEMG RUN YUAN TECHNOLOGY CO.,LTD					
GP		HF		DRWN:		PART NO.:			
DEC		TOL		Qing Wang 4/20'13		FP0510X-0XXXXGL			
X.		±--		CHKD:		TITLE: 0.5P 1.0H FPC (BACK-FLIP)-ASSY			
X.X		±0.15		Jack Wang 4/20'13		DRAWING NO.:			
X.XX		±0.05		APPD:					
X.XXX		±--		Bob Sun 4/22'13					
SHEET:		2/2				UNIT	SCALE	SIZE	REV
						mm	10:1	A4	A1